

General Description

The WST3392 is the highest performance trench Dual N-ch MOSFETs with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the small power switching and load switch applications.

The WST3392 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent C_{dv}/dt effect decline
- Green Device Available

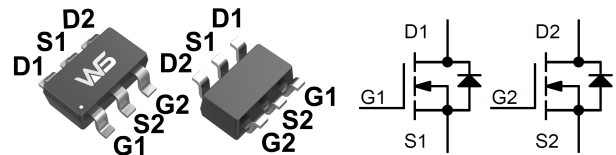
Product Summary

| BVDSS | $R_{DS(ON)}$ | I_D |
|-------|--------------|-------|
| 30V | 40m Ω | 3.7A |

Applications

- Power management in portable and battery operated products
- One cell battery pack protection

SOT-23-6L Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|----------------------|---------------------------------------------|------------|------------|
| V_{DS} | Drain-Source Voltage | 30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D@T_C=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 4.5V^1$ | 3.7 | A |
| $I_D@T_C=70^\circ C$ | Continuous Drain Current, $V_{GS} @ 4.5V^1$ | 3.0 | A |
| I_{DM} | Pulsed Drain Current ² | 20 | A |
| $P_D@T_A=25^\circ C$ | Total Power Dissipation ³ | 1.15 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--------------------------------------------------|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient ¹ | --- | 110 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 80 | $^\circ C/W$ |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|------------------------------------------------|----------------------------------------------------------------------------------------------------------------|------|-------|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 30 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BVDSS Temperature Coefficient | Reference to 25°C, I _D =1mA | --- | 0.028 | --- | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =10V, I _D =3.5A | --- | 40 | 50 | mΩ |
| | | V _{GS} =6V, I _D =2A | --- | 45 | 65 | |
| | | V _{GS} =4.5V, I _D =2A | --- | 58 | 73 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.0 | 1.5 | 2.0 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -3.21 | --- | mV/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =30V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =30V, V _{GS} =0V, T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |
| g _{fs} | Forward Transconductance | V _{DS} =5V, I _D =5A | --- | 12 | --- | S |
| R _g | Gate Resistance | V _{DS} =0V, V _{GS} =0V, f=1MHz | --- | 4 | 6 | Ω |
| Q _g | Total Gate Charge (4.5V) | V _{DS} =15V, V _{GS} =10V, I _D =3.5A | --- | 4.05 | 5 | nC |
| Q _{gs} | Gate-Source Charge | | --- | 0.55 | 0.8 | |
| Q _{gd} | Gate-Drain Charge | | --- | 1.0 | 1.8 | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =15V, V _{GEN} =10V, R _G =3Ω I _D =1.0A, R _L =4.2Ω. | --- | 4.5 | --- | ns |
| T _r | Rise Time | | --- | 1.5 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 18.5 | --- | |
| T _f | Fall Time | | --- | 15.5 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =15V, V _{GS} =0V, f=1MHz | --- | 170 | 210 | pF |
| C _{oss} | Output Capacitance | | --- | 35 | 45 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 23 | 30 | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|------------------------------------------|------------------------------------------------------------------|------|------|------|------|
| I _S | Continuous Source Current ^{1,4} | V _G =V _D =0V, Force Current | --- | --- | 1.5 | A |
| I _{SM} | Pulsed Source Current ^{2,4} | | --- | --- | 3.5 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _{SD} =3.5A, T _J =25°C | --- | --- | 1.0 | V |
| t _{rr} | Reverse Recovery Time | I _F =3.5A, dI/dt=100A/μs, T _J =25°C | --- | 7.5 | --- | nS |
| Q _{rr} | Reverse Recovery Charge | | --- | 2.5 | --- | nC |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

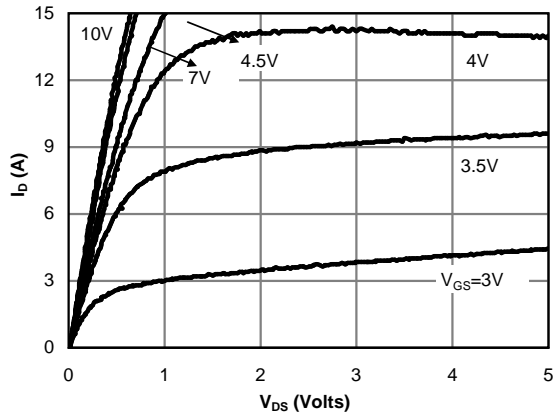


Fig 1: On-Region Characteristics (Note E)

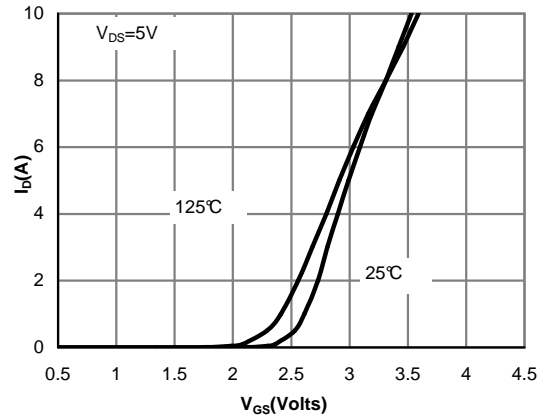


Figure 2: Transfer Characteristics (Note E)

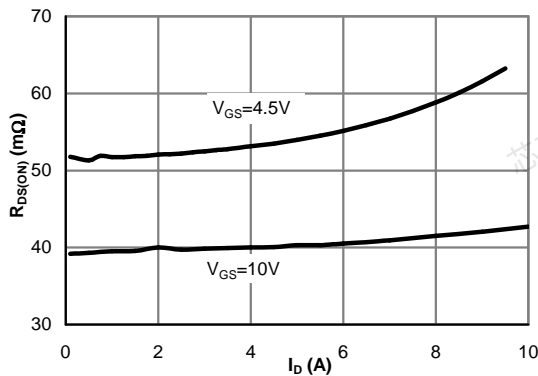


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

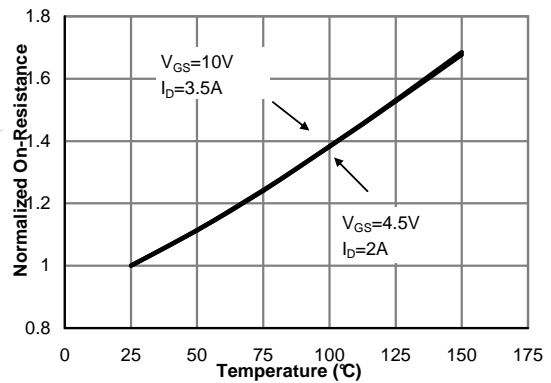


Figure 4: On-Resistance vs. Junction Temperature (Note E)

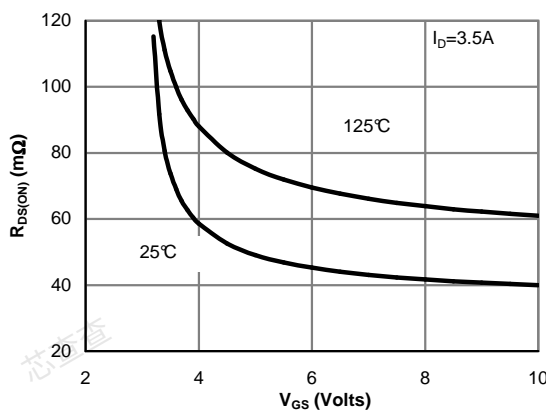


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

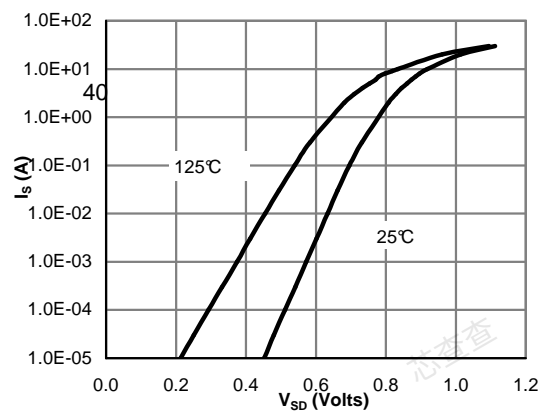


Figure 6: Body-Diode Characteristics (Note E)

Typical Characteristics

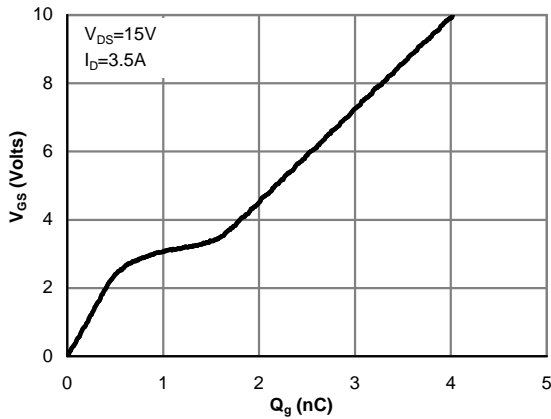


Figure 7: Gate-Charge Characteristics

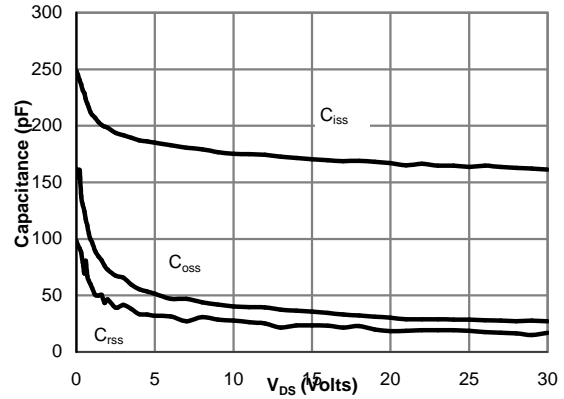


Figure 8: Capacitance Characteristics

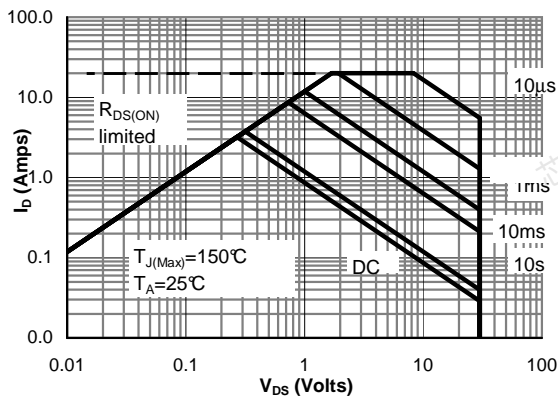


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

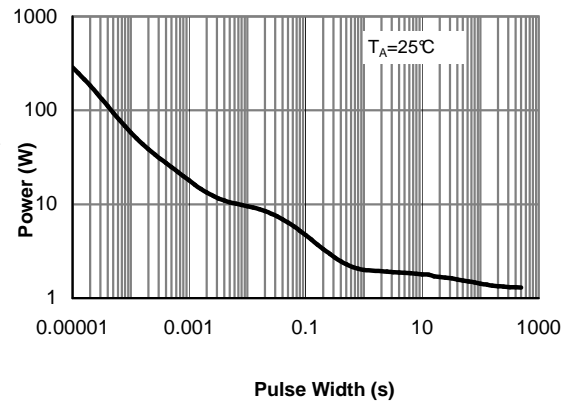


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

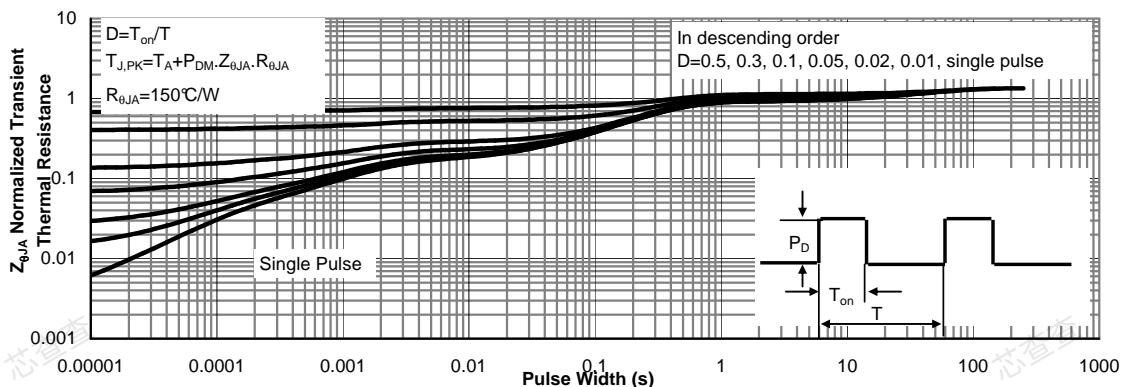


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

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